Peter Yau

Address: No 17--19# LiXin Road LongGang district ShenZhen
skype: live:.cid.60f85a516e382127
www.linkedin.com/in/peter-y-a9309490

- Leading Independent Distributor of EE Components
- Bilingual in Cantonese and English languages

Dedicated Professional with over 10 years of expertise in designing and optimizing embedded & RF Hardware and Software systems and integrating AI technologies.
Adept at leading cross-functional projects from concept to production, with a focus on improving system performance and efficiency.
Specialized in low-power IoT devices, AI-powered embedded solutions, and real-time systems. Proven ability to enhance functionality through AI integration, reducing power consumption, and improving product reliability.

PROFESSIONAL EXPERIENCE

Co-Founder & CTO, Volentech Inc. California *// Sep 2021 – Present*

- Design and develop the most efficient and technologically advanced engineering solutions for our customers by satisfying the end-user requirements and continuous customer feedback.
- Develop innovative products from scratch and oversee production chain as well.
- Explore and integrate AI technologies to enhance the functionality and performance of embedded systems.

Product Engineer, SKNT (Shenzhen Kingbird Network Technology Co., Ltd), Shenzhen *// Mar 2018 – Dec 2020*

- Design and development for embedded systems, focusing on GPS, AGPS systems, wireless technologies Wi-Fi, Bluetooth, RFID, LoRa and 4G/5G.
- Collaborating with cross-functional teams, including hardware, software, and system engineers, to ensure product performance, integration, and optimization.
- Responsible for troubleshooting, validating, and ensuring the scalability and reliability of the products in real-world applications.

RF & Embedded Systems Engineer, SHSTE (Shenzhen Haiyi Science and Technology Electronics Co., Ltd), Shenzhen *// Jan 2017 – Feb 2018*

- Responsible for designing and developing RF systems and embedded solutions, integrating hardware and software to optimize performance for wireless communication and radar applications.
- Engineered PCB board designs and conducted reviews to overcome issues with EMC/EMI, ESD, signal conditioning and Power isolation compliant to RF standards of ITU-R M, F series.

TECHNICAL SKILLS

- **Programming Languages:** C, C++, C#, VHDL/Verilog, Python, JavaScript
- **Embedded Technologies**
  - ✓ Microcontrollers: ARM Cortex-M, Esp32, AVR, PIC, MSP430, Renesas RX
  - ✓ SOCs: Raspberry Pi, Rockchip RK33, NXP, Jetson Nano/TX2, Xilinx Zynq UltraScale+, ESP32 SoC, FPGA, DSP, RTOS
  - ✓ Embedded AI: TensorFlow Lite, TinyML, NVIDIA Jetson
- **Hardware Design and Simulation**
  - ✓ PCB Design, Circuit Design, Radar System & Signal Processing Design, RF Design
  - ✓ Proteus, Ni Multisim, SPICE, MATLAB/SIM…, CST, ADS
- **Wireless Communication and IoT:**
  - ✓ Wi-Fi, BLE, 4/5G, ZigBee, Lora, RFID, ISM/SRD, GPS
  - ✓ IoT Protocols: MQTT, CoAP
- **AI Integration**
  - ✓ AI Frameworks: TensorFlow, Keras, OpenCV
  - ✓ AI machine vision: Smart Camera, Home Automation
- **Testing and Debugging**
- **Problem-Solving**
- **Version Control**
- **Project Leadership**
- **Collaboration and Teamwork**
- **Clear Communication**

EDUCATION

South China University of Technology (SCUT)
Master of Science, Radio Engineering // Mar 2014 - Oct 2016

- Diligence in Embedded & RF Hardware Design and Software Development.

South China University of Technology (SCUT)
Bachelor of Science, Electronics Engineering // Apr 2009 - Sep 2013

- Diligence in Digital/Analog/Mixed-signal Design.